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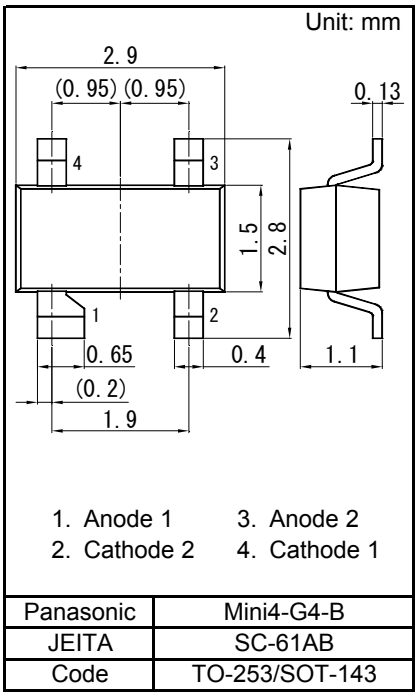
Switching Diode

Panasonic DA4X101F0R

DA4X101F0R

Silicon epitaxial planar type

For high speed switching circuits



Panasonic	Mini4-G4-B
JEITA	SC-61AB
Code	TO-253/SOT-143

■ Features
- Small reverse current IR
- Short reverse recovery time trr
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 22

■ Basic Part Number :
Dual DA2J101 (Parrarel, oppositely arranged)

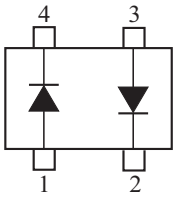
■ Packaging
Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter		Symbol	Rating	Unit
Reverse voltage		VR	80	V
Maximum peak reverse voltage		VRM	80	V
Forward current (Average)	Single	IF(AV)	100	mA
	Double		75	
Repetitive peak forward current	Single	IFRM	225	mA
	Double		170	
Non-repetitive peak forward surge current *1	Single	IFSM	500	mA
	Double		375	
Junction temperature		Tj	150	°C
Operating ambient temperature		Topr	-40 to +85	°C
Storage temperature		Tstg	-55 to +150	°C

Note) *1: t = 1 s

Internal Connection

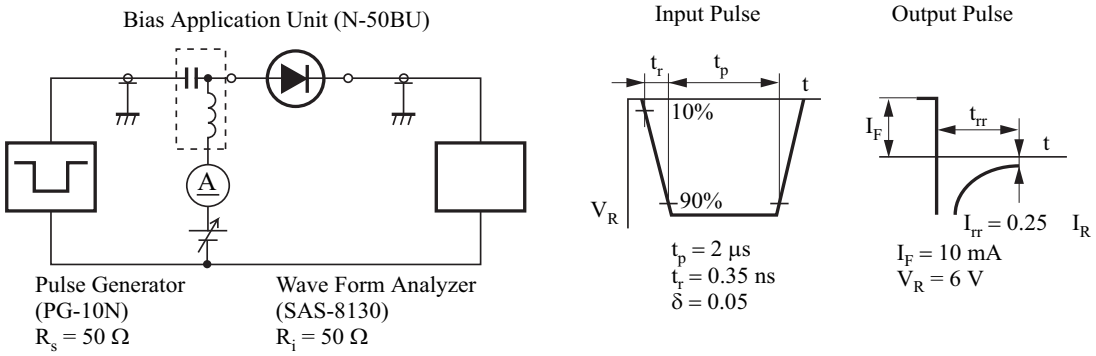


Established : 2009-11-26
Revised : 2013-06-19

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 100 mA		0.95	1.20	V
Reverse voltage	VR	IR = 100 µA	80			V
Reverse current	IR	VR = 80 V			100	nA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		0.9	2.0	pF
Reverse recovery time *1	trr	IF = 10 mA , VR = 6 V Irr = 0.25 x IR			3	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
2. Absolute frequency of input and output is 100 MHz.
3. *1: trr test circuit



Established : 2009-11-26
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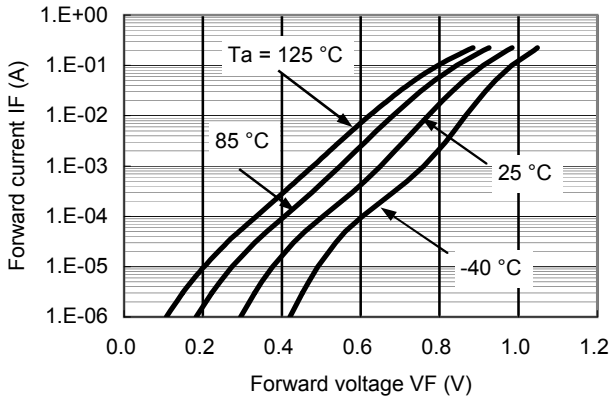
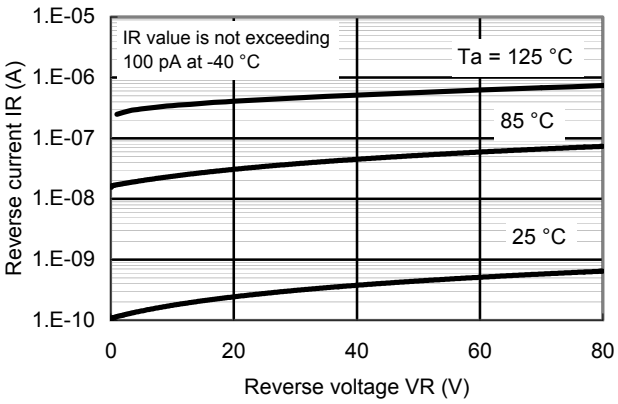
Technical Data (reference)

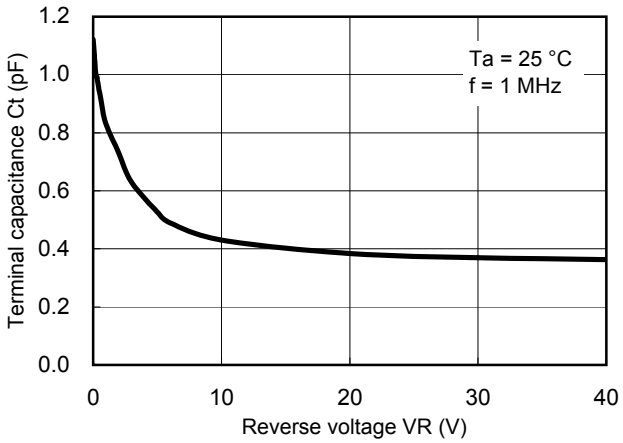
IF - VF



IR - VR



Ct - VR



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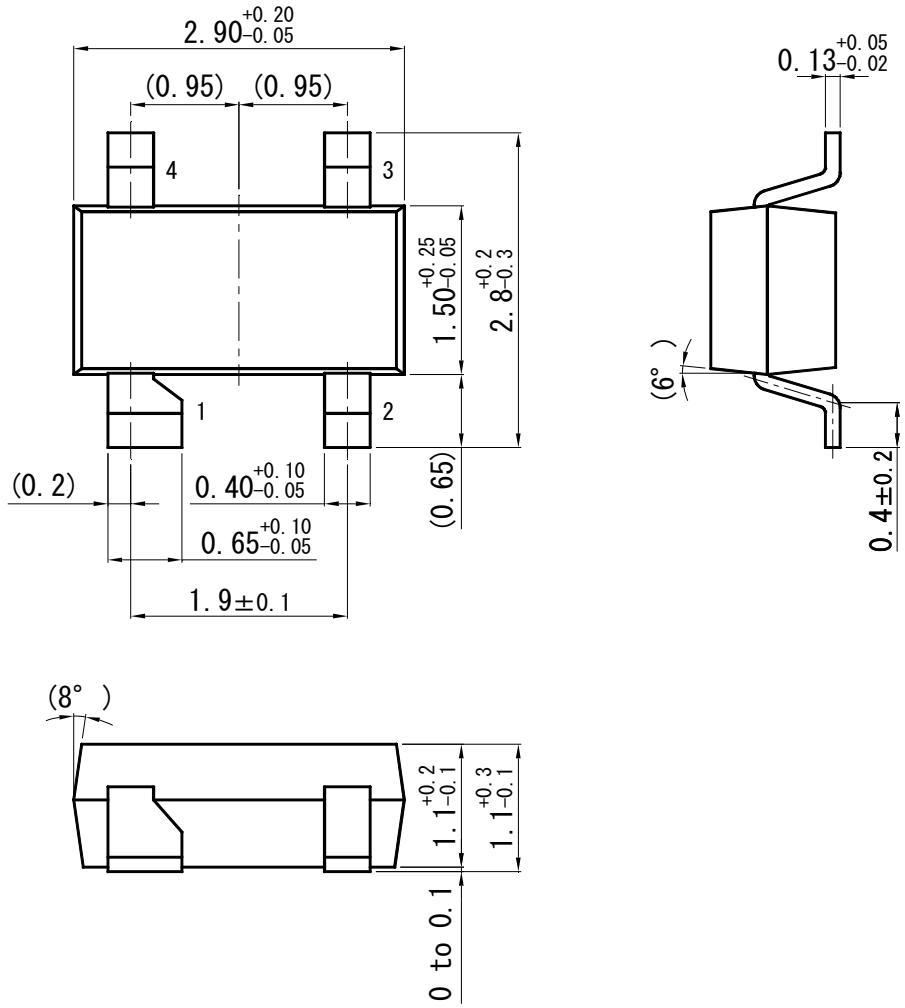
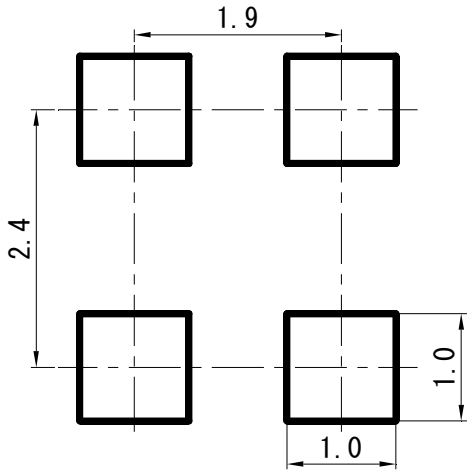
Mini4-G4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



Established : 2009-11-26
Revised : 2013-06-19

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